

## 30V Dual N+P Channel Power MOSFET

### Feature

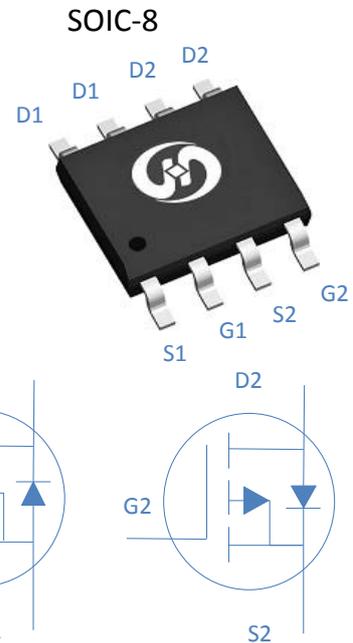
- ◇ High Speed Power Switching, Logic Level
- ◇ Enhanced Avalanche Ruggedness
- ◇ Lead Free, Halogen Free

	N-CH	P-CH	
$V_{DS}$	30	-30	V
$R_{DS(on),max}$	28	45	m $\Omega$
$I_D$ (Silicon Limited)	7	-6	A

### Application

- ◇ Hard Switching and High Speed Circuit
- ◇ BLDC motor

Part Number	Package	Marking
HTS280C03	SO8	TS280C03



### Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ (unless otherwise specified)

Parameter	Symbol	Conditions	N-CH	P-CH	Unit
Continuous Drain Current (Silicon Limited)	$I_D$	$T_A=25^\circ\text{C}$	7	-6	A
		$T_A=100^\circ\text{C}$	6	-5	
Drain to Source Voltage	$V_{DS}$	-	30	-30	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$		V
Pulsed Drain Current	$I_{DM}$	-	28	-24	A
Power Dissipation	$P_D$	$T_A=25^\circ\text{C}$	2		W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 150		$^\circ\text{C}$

### Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$
Thermal Resistance Junction-Case	$R_{\theta JC}$	25	$^\circ\text{C/W}$

**N-Channel Electrical Characteristics at  $T_J=25^{\circ}\text{C}$  (unless otherwise specified)**
**Static Characteristics**

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	1.5	3.0	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS}=0V, V_{DS}=24V, T_J=25^{\circ}\text{C}$	-	-	1	$\mu A$
		$V_{GS}=0V, V_{DS}=20V, T_J=125^{\circ}\text{C}$	-	-	25	
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=7A$	-	24	28	m $\Omega$
		$V_{GS}=4.5V, I_D=6A$	-	33	44	
Transconductance	$g_{fs}$	$V_{DS}=5V, I_D=7A$	-	14	-	S

**Dynamic Characteristics**

Input Capacitance	$C_{iss}$		-	520	-	pF
Output Capacitance	$C_{oss}$	$V_{GS}=0V, V_{DS}=15V, f=1\text{MHz}$	-	88	-	
Reverse Transfer Capacitance	$C_{rss}$		-	62	-	
Total Gate Charge	$Q_g(10V)$		-	11.5	-	nC
Gate to Source Charge	$Q_{gs}$	$V_{DD}=15V, I_D=7A, V_{GS}=10V$	-	1.6	-	
Gate to Drain (Miller) Charge	$Q_{gd}$		-	2.8	-	
Turn on Delay Time	$t_{d(on)}$		-	11	-	ns
Rise time	$t_r$	$V_{DD}=10V, I_D=1A, V_{GS}=10V,$	-	16	-	
Turn off Delay Time	$t_{d(off)}$	$R_G=6\Omega,$	-	36	-	
Fall Time	$t_f$		-	20	-	

**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_F=2.3A$	-		1.3	V
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Fig 1. Typical Output Characteristics

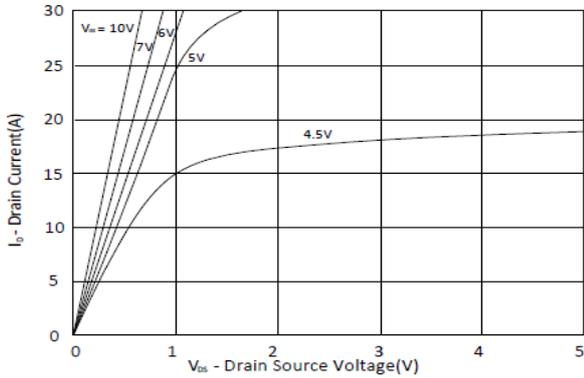


Figure 2. On-Resistance vs. Gate-Source Voltage

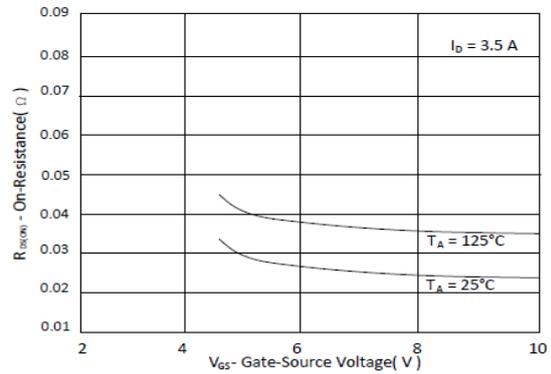


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

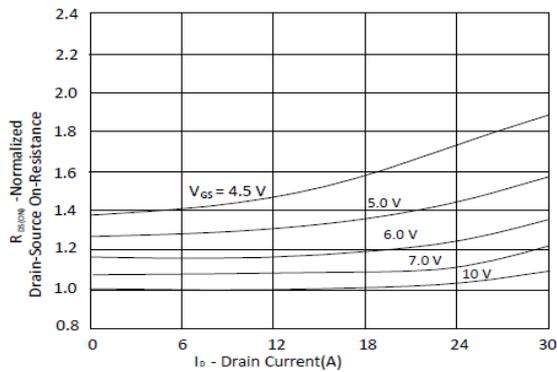


Figure 4. Normalized On-Resistance vs. Junction Temperature

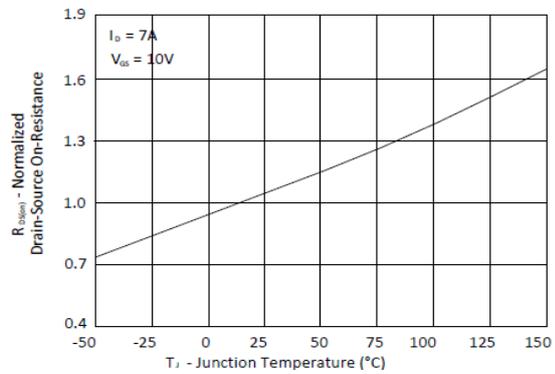


Figure 5. Typical Transfer Characteristics

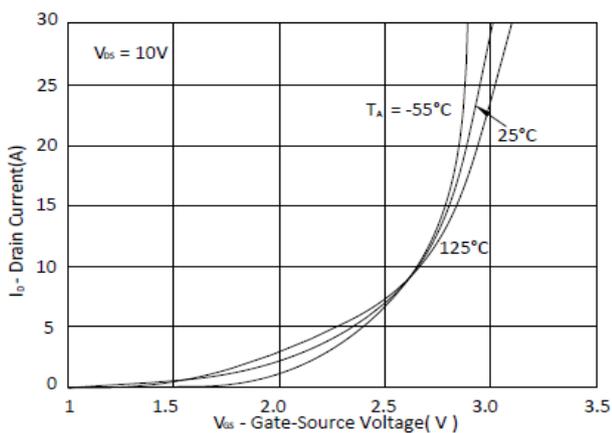


Figure 6. Typical Source-Drain Diode Forward Voltage

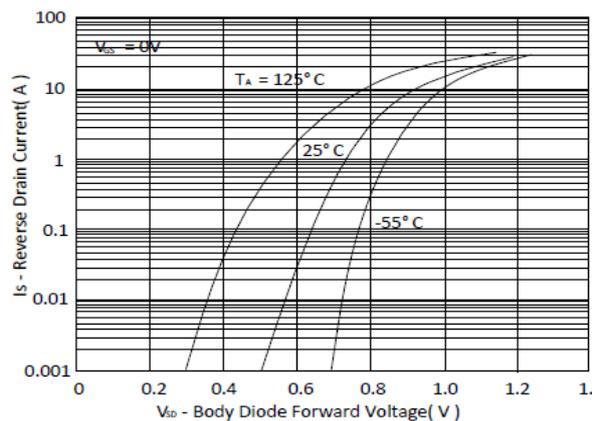


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

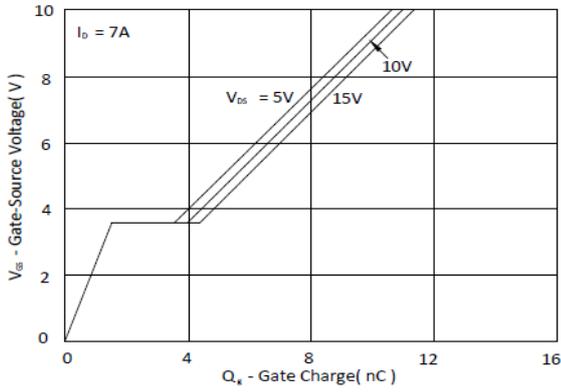


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

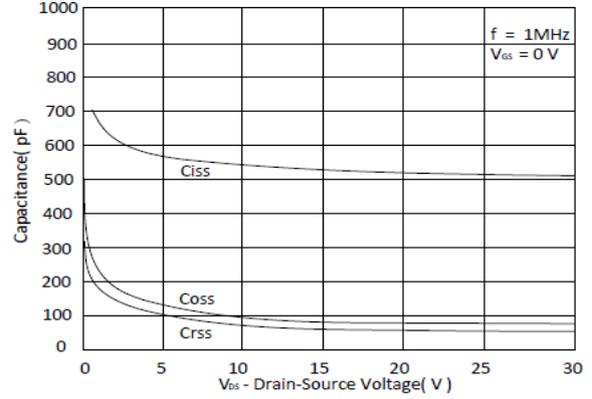


Figure 9. Maximum Safe Operating Area

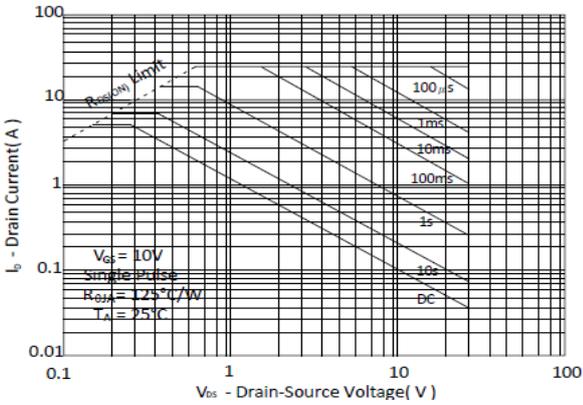


Figure 10. Single Pulse Maximum Power Dissipation

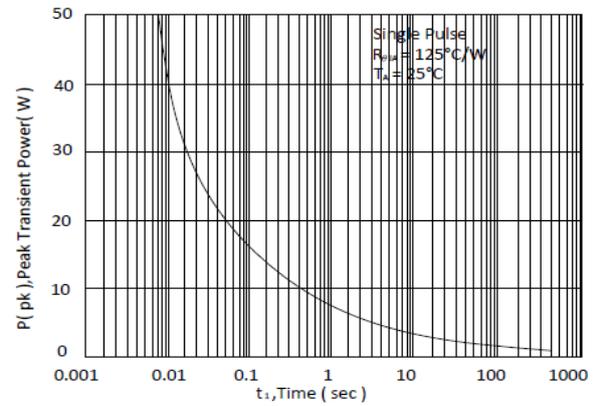
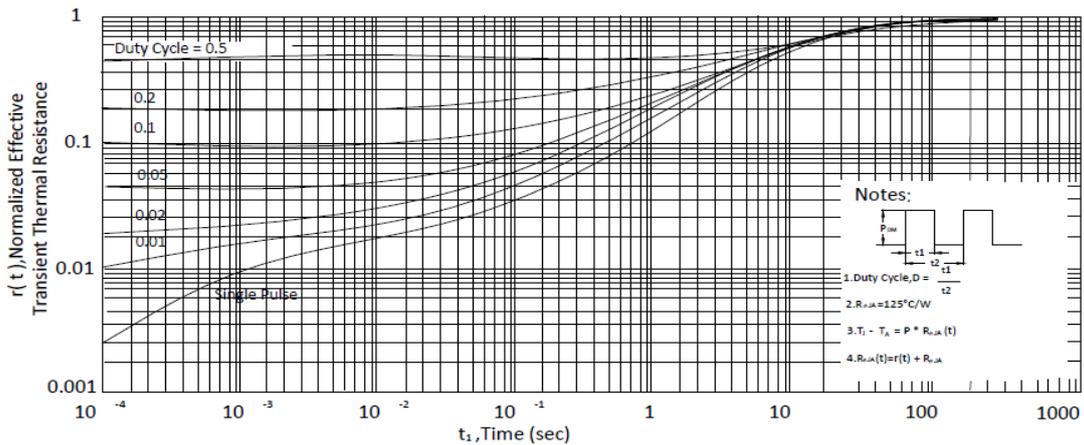
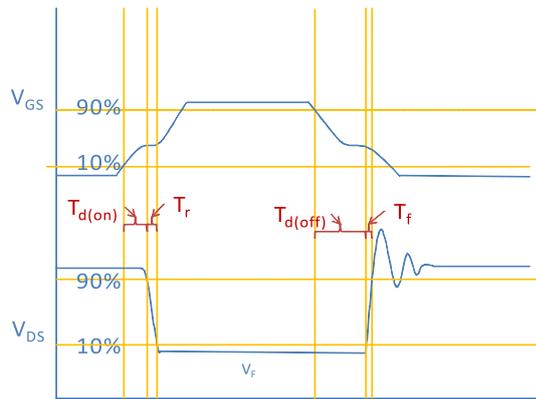
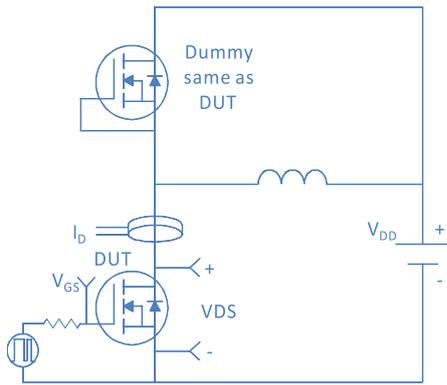


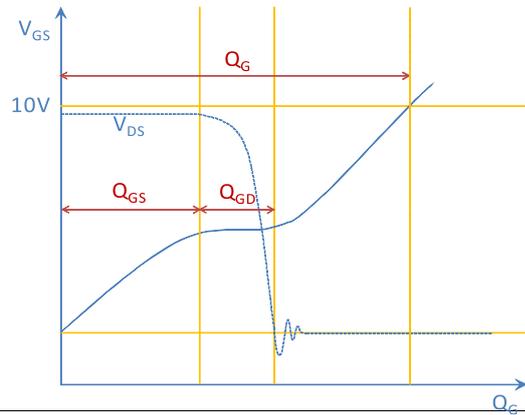
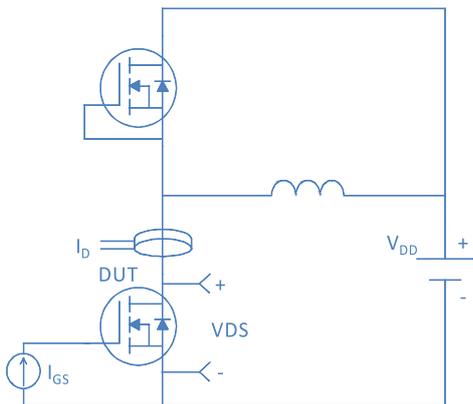
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient



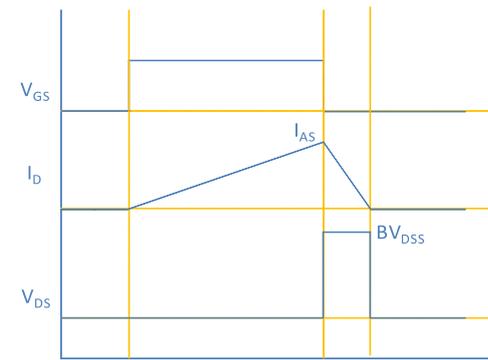
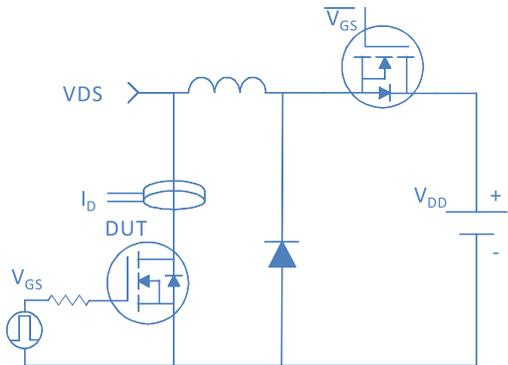
Inductive switching Test



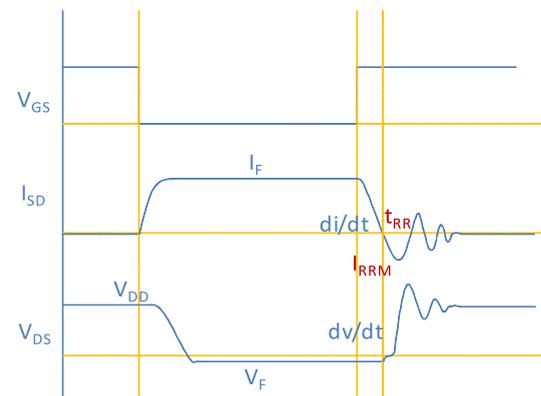
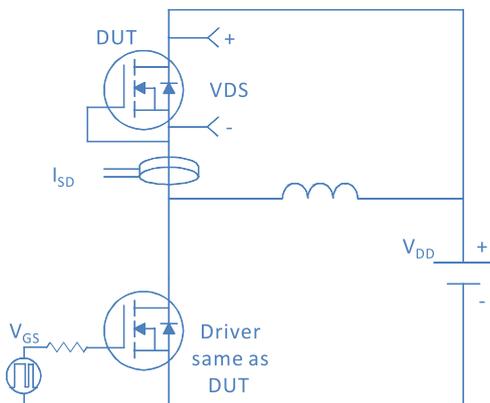
Gate Charge Test



Uclamped Inductive Switching (UIS) Test



Diode Recovery Test



**P-Channel Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.0	-1.5	-3.0	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS}=0V, V_{DS}=-24V, T_j=25^\circ\text{C}$	-	-	-1	$\mu A$
		$V_{GS}=0V, V_{DS}=-20V, T_j=125^\circ\text{C}$	-	-	-25	
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-6A$	-	39	45	m $\Omega$
		$V_{GS}=-4.5V, I_D=-5A$	-	56	72	
Transconductance	$g_{fs}$	$V_{DS}=-5V, I_D=-6A$	-	16	-	S

**Dynamic Characteristics**

Input Capacitance	$C_{iss}$		-	820	-	pF
Output Capacitance	$C_{oss}$	$V_{GS}=0V, V_{DS}=-15V, f=1\text{MHz}$	-	122	-	
Reverse Transfer Capacitance	$C_{rss}$		-	97	-	
Total Gate Charge	$Q_g (10V)$		-	9.0	-	nC
Gate to Source Charge	$Q_{gs}$	$V_{DD}=-15V, I_D=-6A, V_{GS}=-10V$	-	2.2	-	
Gate to Drain (Miller) Charge	$Q_{gd}$		-	2.5	-	
Turn on Delay Time	$t_{d(on)}$		-	10	-	ns
Rise time	$t_r$	$V_{DD}=-10V, I_D=-1A, V_{GS}=-10V,$	-	15	-	
Turn off Delay Time	$t_{d(off)}$	$R_G=6\Omega,$	-	28	-	
Fall Time	$t_f$		-	15	-	

**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_F=-2.3A$	-		-1.3	V
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Fig 1. Typical Output Characteristics

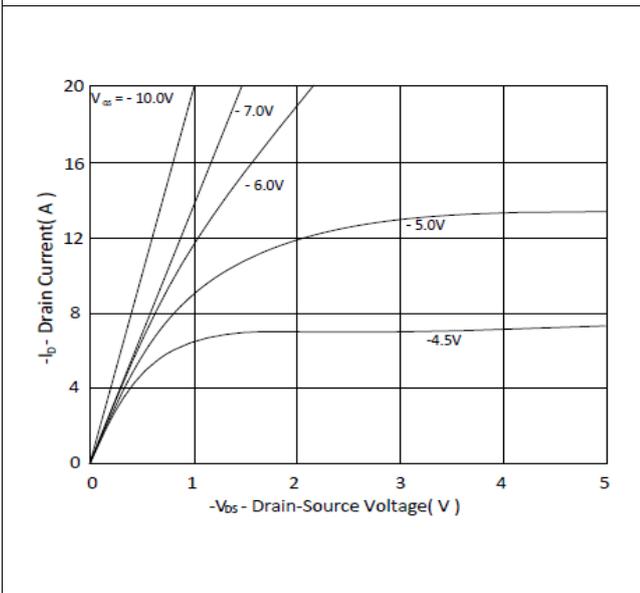


Figure 2. On-Resistance vs. Gate-Source Voltage

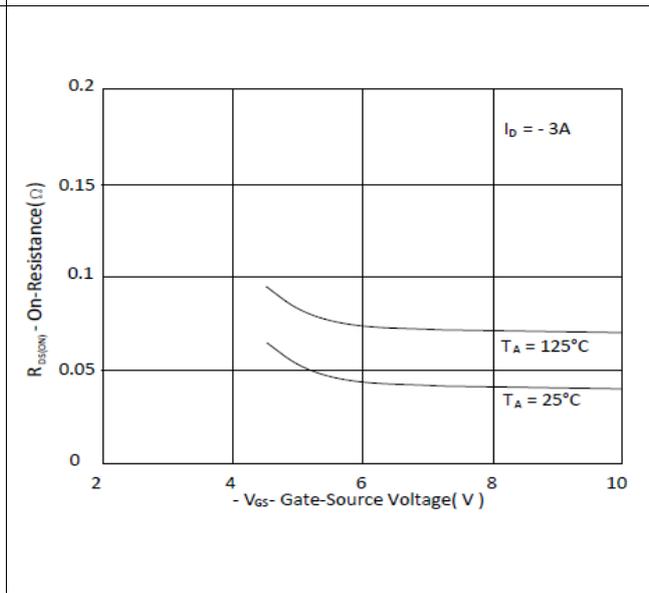


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

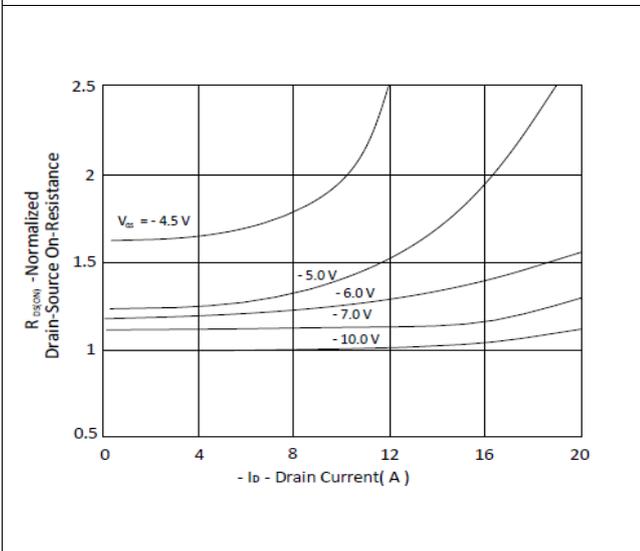


Figure 4. Normalized On-Resistance vs. Junction Temperature

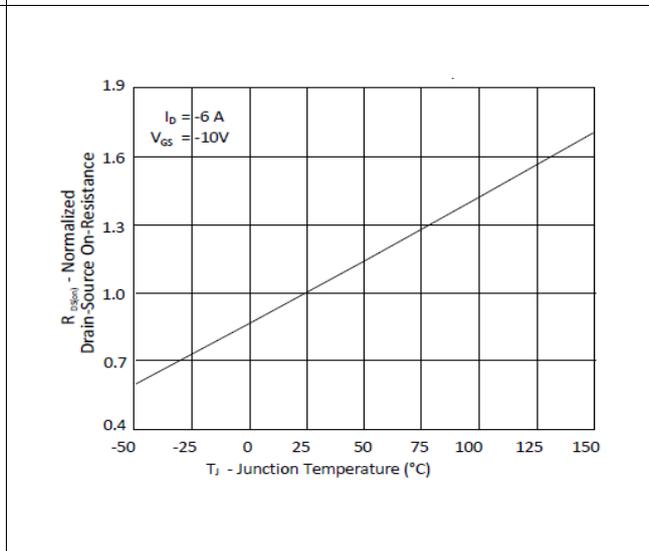


Figure 5. Typical Transfer Characteristics

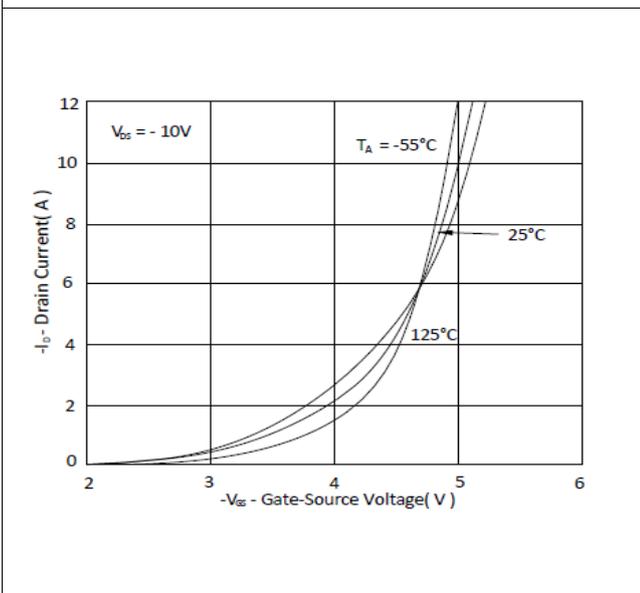


Figure 6. Typical Source-Drain Diode Forward Voltage

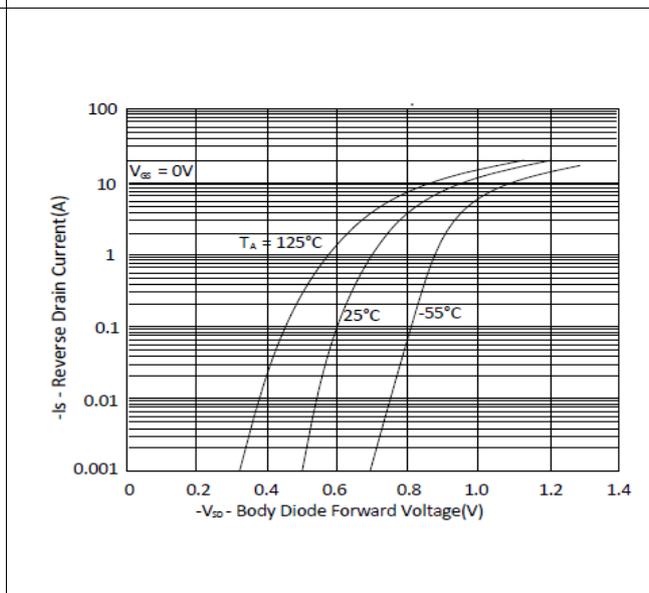


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

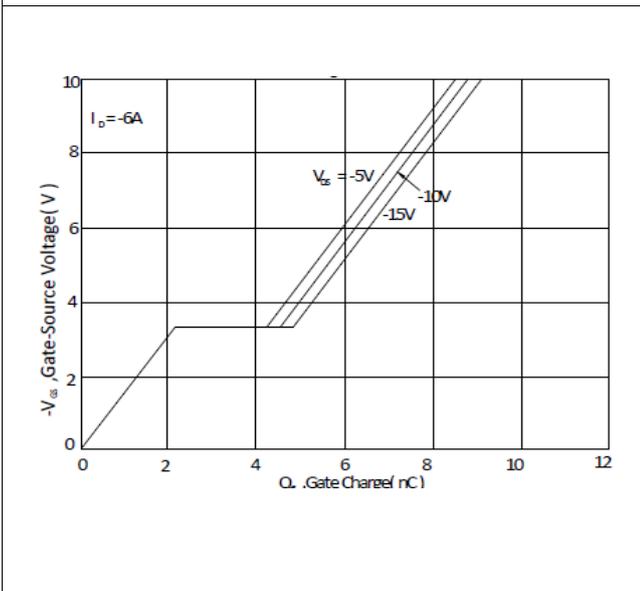


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

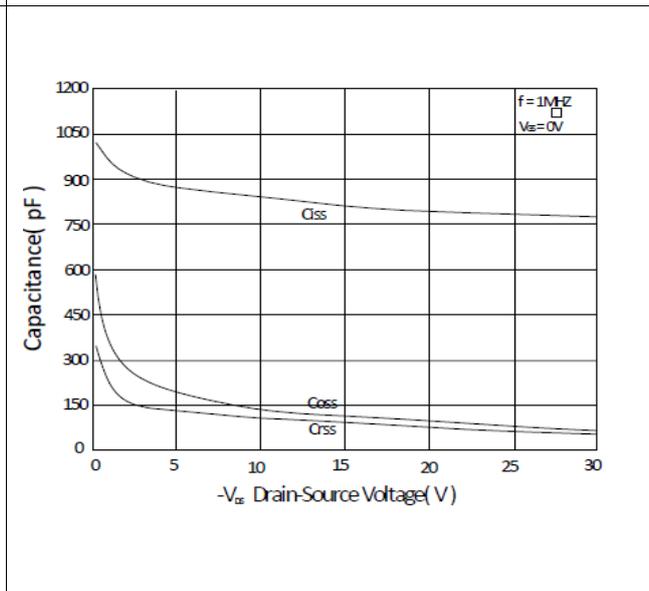


Figure 9. Maximum Safe Operating Area

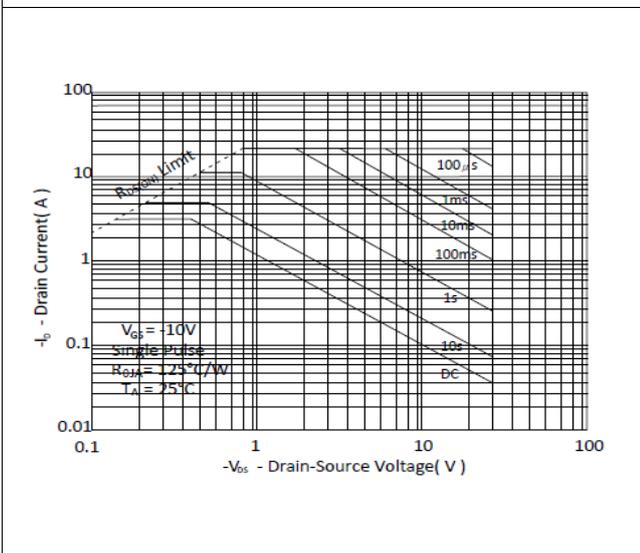


Figure 10. Single Pulse Maximum Power Dissipation

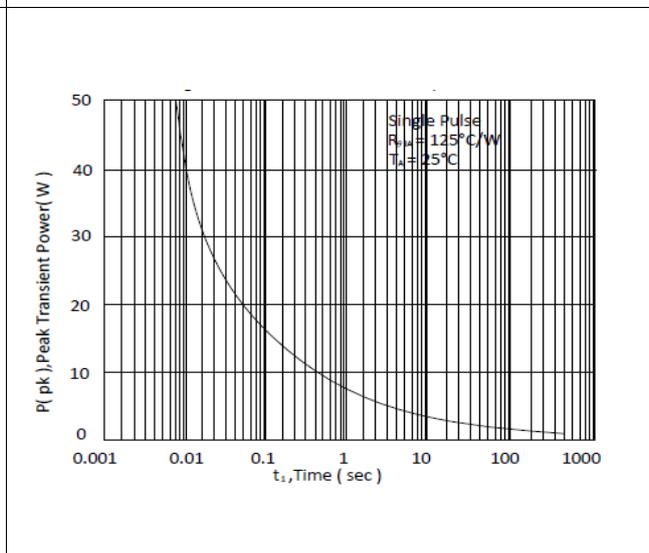
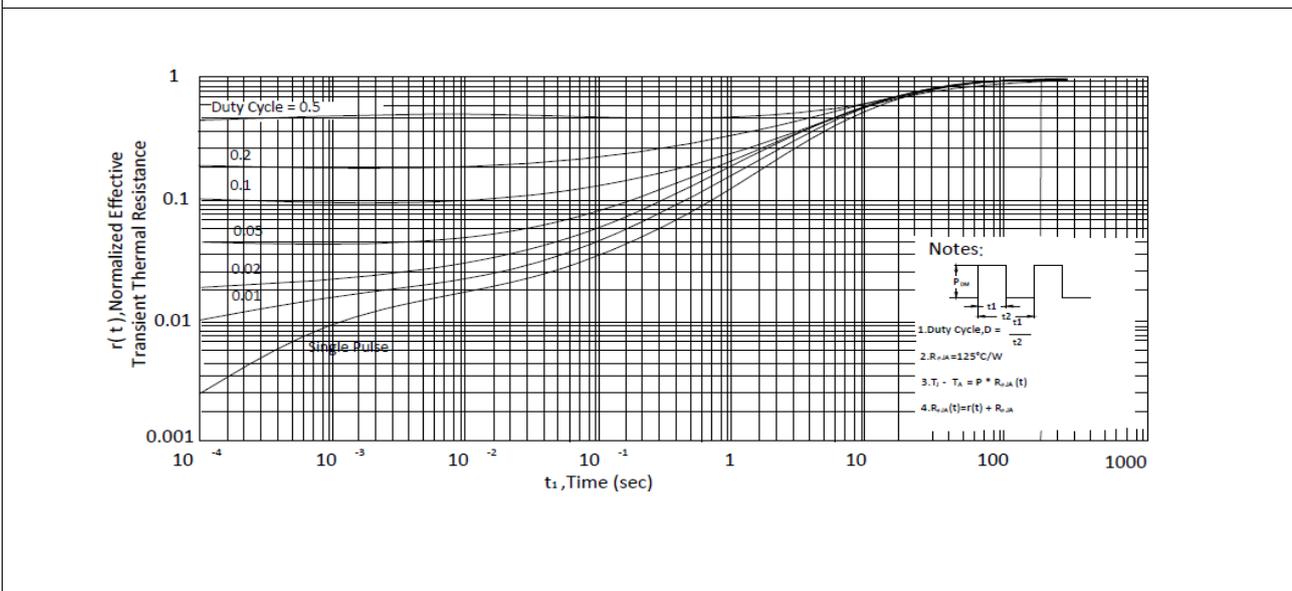
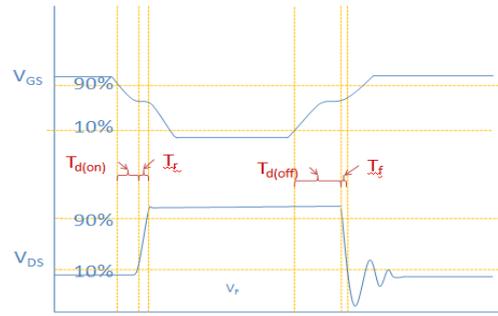
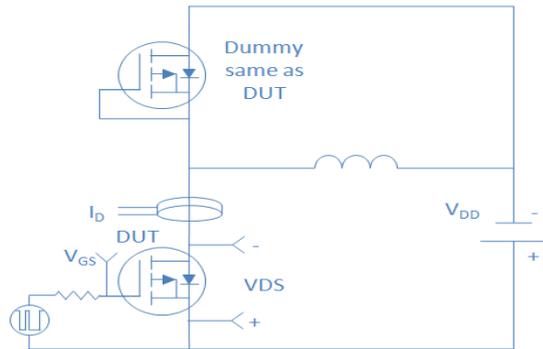


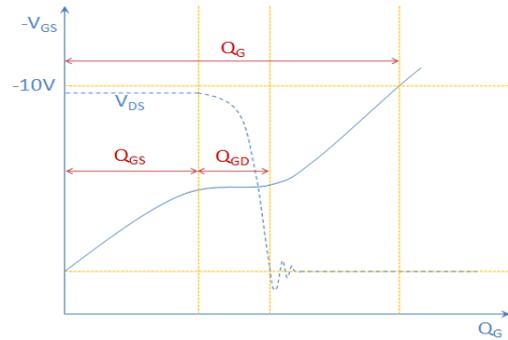
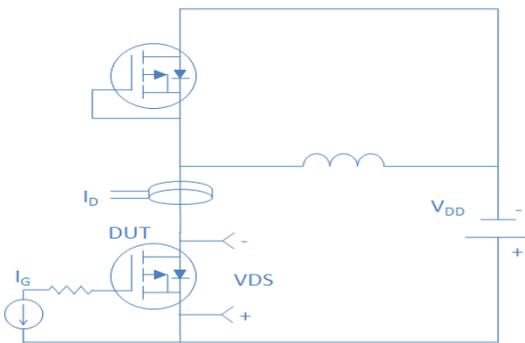
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient



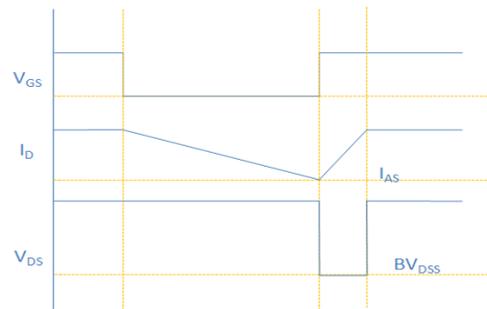
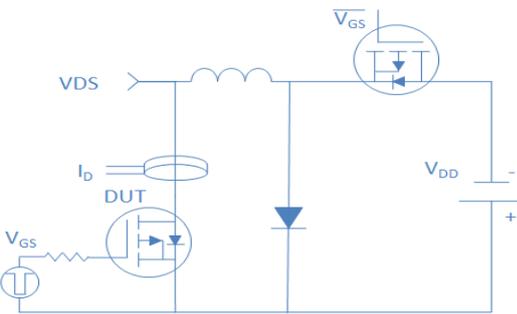
Inductive switching Test



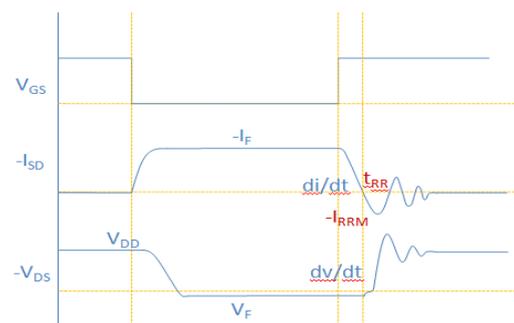
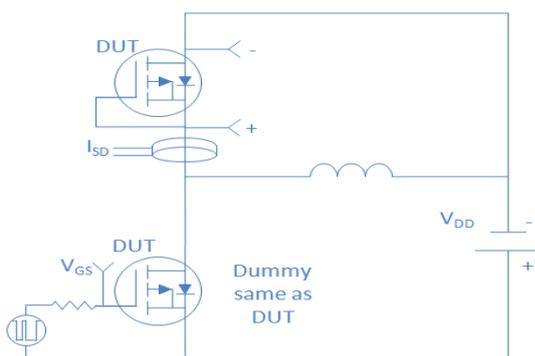
Gate Charge Test



Uclamped Inductive Switching (UIS) Test

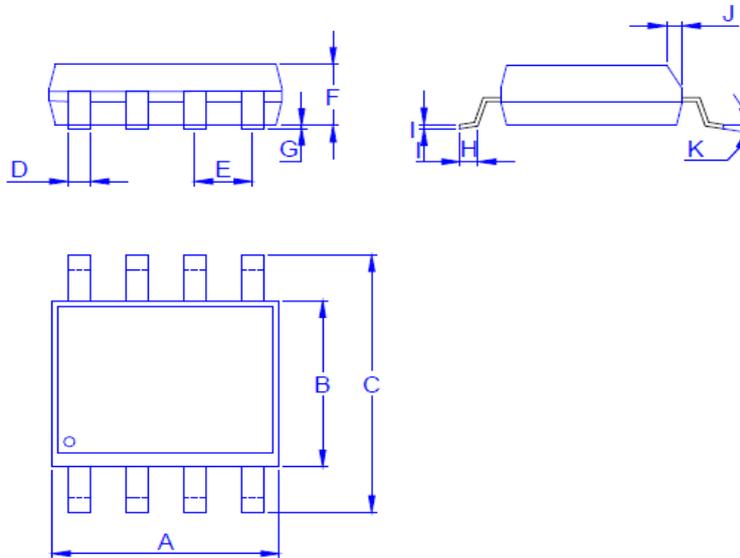


Diode Recovery Test



Package Outline

SOIC-8, 8leads



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K
Min.	4.70	3.70	5.80	0.33		1.20	0.08	0.40	0.19	0.25	0°
Typ.					1.27						
Max.	5.10	4.10	6.20	0.51		1.62	0.28	0.83	0.26	0.50	8°